

Leaded flux cored solder wire

JM-20



- Excellent solderability, very fast wetting
- High surface insulation resistance and non-corrosive, cleaning may be eliminated
- Very little spitting of solder, very low fume levels
- Clear flux residue offers superior cosmetics

◆ Product specifications

Product		JM - 20
Composition (%)		Sn60 Pb40
Flux content (%)		1.0 - 3.0
Halide content (%)		0.0
Silver chromate paper test		No discoloration
Solder spread factor (%)		90
Solder wetting speed*1 (sec.)		< 0.5
Aqueous solution resistivity*2 ($\Omega \bullet \text{cm}$)		$> 1 \times 10^5$
Surface insulation resistance*3	Initial value (Ω)	$> 1 \times 10^{13}$
	After humidification (Ω)	$> 1 \times 10^{12}$
Copper corrosion*4	Copper plate	Passed
	Copper mirror	Passed
Flux residue stickiness (by chalk powder)		No attachment
Wire diameter (mm)		0.3, 0.4, 0.5, 0.6, 0.8, 1.0, 1.2, 1.6
Shelf life		3 years

*Specifications are subject to change.

*1. Solder wetting speed:

By Meniscograph with copper plate (30×7×0.2mm) at 230°C

*2. Aqueous solution resistivity:

In accordance with MIL specifications.

*3. SIR:

In accordance with JIS Z 3197 (40°C×90%RH×96Hr)

*4. Copper corrosion:

In accordance with JIS